## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2835

Applicant: George Hsieh

Title: ELECTRONIC ASSEMBLY WITH SOLDERABLE HEAT SINK AND METHODS OF

**MANUFACTURE** 

Docket No.:

884.462US1

Filed:

June 29, 2001

Examiner:

Gregory Thompson

NUG 2 5 2**003** 

Serial No.: 09/897320

Due Date: N/A

Group Art Unit: 2835

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

 $\underline{X}$  A return postcard.

X A Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 4 cited documents.

X A copy of the International Search Report in PCT/US02/14870, mailed May 22, 2003.

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

Atty: Ann M. McCrackin

Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 22 day of \_\_\_\_\_\_\_, 2003.

KACIA

Name

Signature XI

**Customer Number 21186** 

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

(GENERAL)

S/N 09/897320 <u>PATENT</u>

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: George Hsieh Examiner: Gregory Thompson

Serial No.: 09/897320 Group Art Unit: 2835

Filed: June 29, 2001 Docket: 884.462US†
Title: ELECTRONIC ASSEMBLY WITH SOLDERABLE HEAT SINK AND

METHODS OF MANUFACTURE

Assignee: Intel Corporation Customer No.: 21186

## SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant requests that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicant with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(1) and 37 C.F.R. §1.97(e)(1), Applicant states that each item of information contained in the Supplemental Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Supplemental Information Disclosure Statement. The relevant International Search Report in PCT/US02/14870, mailed May 22, 2003, is enclosed.

It is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if a final action under §1.113, a notice of allowance under §1.311, or an action that otherwise closes prosecution in the application has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

Serial No :09 897320

Filing Date: June 29, 2001

Dkt: 884.462US1 (INTEL)

Title: ELFCTRONIC ASSEMBLY WITH SOLDERABLE HEAT SINK AND METHODS OF MANUFACTURE

Assignee: Intel Corporation

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

**GEORGE HSIEH** 

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. Attorneys for Intel Corporation

P.O. Box 2938

Minneapolis, Minnesota 55402

(612) 349-9592

Date (hug. 22, 2003

By Ann M. McCrackin

Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 22 day of Account., 2003.

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## Substitute for form 1449A-PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)

Application Number	09/897320
Filing Date	June 29, 2001
First Named Inventor	Hsieh, George
Group Art Unit	2835
Examiner Name	Thompson, Gregory

Sheet 1 of 1

US PATENT DOCUMENTS						
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-5,375,652	12/27/1994	Matsunaga, K., et al.	165	80.3	08/10/1993
	US-5,926,371	07/20/1999	Dolbear, Thomas P.	361	704	04/25/1997

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T²
	JP-10-189841	07/21/1998	Tadayoshi, D	H01L	23/40	
	JP-2000-138483	05/16/2000	Yamaguchi, Seiji	H05K	7/20	

	OTHER	R DOCUMENTS NON PATENT LITERATURE DOCUMENTS	
Examiner	Cite	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item	T <sup>2</sup>
Initials*	No 1	(book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s),	
		publisher, city and/or country where published.	1